



**THE DATASHEET OF
PCA9554BS3,118**





PCA9554; PCA9554A

8-bit I²C-bus and SMBus I/O port with interrupt

Rev. 10 — 8 November 2017

Product data sheet

1. General description

The PCA9554 and PCA9554A are 16-pin CMOS devices that provide 8 bits of General Purpose parallel Input/Output (GPIO) expansion for I²C-bus/SMBus applications and were developed to enhance the NXP Semiconductors family of I²C-bus I/O expanders. The improvements include higher drive capability, 5 V I/O tolerance, lower supply current, individual I/O configuration, 400 kHz clock frequency, and smaller packaging. I/O expanders provide a simple solution when additional I/O is needed for ACPI power switches, sensors, push buttons, LEDs, fans, and so on.

The PCA9554/PCA9554A consist of an 8-bit Configuration register (Input or Output selection); 8-bit Input Port register, 8-bit Output Port register and an 8-bit Polarity Inversion register (active HIGH or active LOW operation). The system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input Port or Output Port register. The polarity of the read register can be inverted with the Polarity Inversion register. All registers can be read by the system master. Although pin-to-pin and I²C-bus address compatible with the PCF8574 series, software changes are required due to the enhancements and are discussed in *Application Note AN469*.

The PCA9554/PCA9554A open-drain interrupt output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed. The power-on reset sets the registers to their default values and initializes the device state machine.

Three hardware pins (A0, A1, A2) vary the fixed I²C-bus address and allow up to eight devices to share the same I²C-bus/SMBus. The PCA9554A is identical to the PCA9554 except that the fixed I²C-bus address is different allowing up to sixteen of these devices (eight of each) on the same I²C-bus/SMBus.

2. Features and benefits

- Operating power supply voltage range of 2.3 V to 5.5 V
- 5 V tolerant I/Os
- Polarity Inversion register
- Active LOW interrupt output
- Low standby current
- Noise filter on SCL/SDA inputs
- No glitch on power-up
- Internal power-on reset
- 8 I/O pins which default to 8 inputs
- 0 Hz to 400 kHz clock frequency



- ESD protection exceeds 2000 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- AEC-Q100 compliance available
- Packages offered: SO16, SSOP16, SSOP20, TSSOP16, HVQFN16 (2 versions: 4 × 4 × 0.85 mm and 3 × 3 × 0.85 mm), and bare die

3. Ordering information

Table 1. Ordering information

| Type number | Topside marking | Package | | |
|----------------|-----------------|----------|--|----------|
| | | Name | Description | Version |
| PCA9554D | PCA9554D | SO16 | plastic small outline package; 16 leads; body width 7.5 mm | SOT162-1 |
| PCA9554AD | PCA9554AD | | | |
| PCA9554DB | 9554DB | SSOP16 | plastic shrink small outline package; 16 leads; body width 5.3 mm | SOT338-1 |
| PCA9554ADB | 9554A | | | |
| PCA9554TS | PCA9554 | SSOP20 | plastic shrink small outline package; 20 leads; body width 4.4 mm | SOT266-1 |
| PCA9554ATS | PA9554A | | | |
| PCA9554PW | 9554DH | TSSOP16 | plastic thin shrink small outline package; 16 leads; body width 4.4 mm | SOT403-1 |
| PCA9554PW/Q900 | 9554DH | | | |
| PCA9554APW | 9554ADH | | | |
| PCA9554BS | 9554 | HVQFN16 | plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 × 4 × 0.85 mm | SOT629-1 |
| PCA9554ABS | 554A | | | |
| PCA9554BS3 | P54 | HVQFN16 | plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 × 3 × 0.85 mm | SOT758-1 |
| PCA9554ABS3 | 54A | | | |
| PCA9554U | - | bare die | - | - |

[1] PCA9554PW/Q900 is AEC-Q100 compliant. Contact i2c.support@nxp.com for PPAP.

3.1 Ordering options

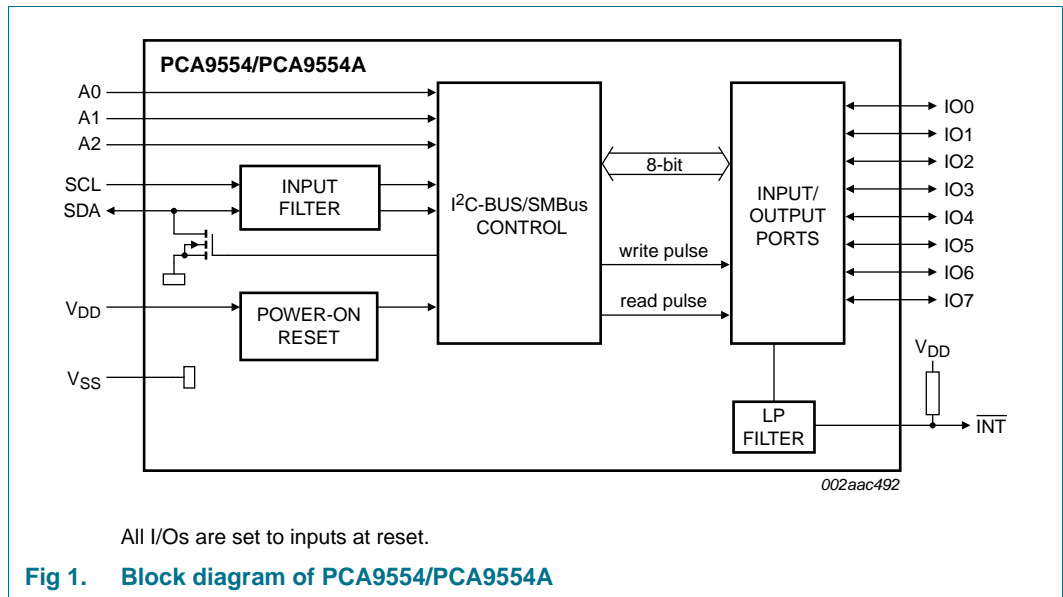
Table 2. Ordering options

| Type number | Orderable part number | Package | Packing method | Minimum order quantity | Temperature |
|-------------|-----------------------|---------|---|------------------------|-------------------------------------|
| PCA9554D | PCA9554D,112 | SO16 | Standard marking * IC's tube - DSC bulk pack | 1920 | T _{amb} = -40 °C to +85 °C |
| | PCA9554D,118 | SO16 | Reel 13" Q1/T1 *standard mark SMD | 1000 | T _{amb} = -40 °C to +85 °C |
| PCA9554AD | PCA9554AD,112 | SO16 | Standard marking * IC's tube - DSC bulk pack | 1920 | T _{amb} = -40 °C to +85 °C |
| | PCA9554AD,118 | SO16 | Reel 13" Q1/T1 *standard mark SMD | 1000 | T _{amb} = -40 °C to +85 °C |
| PCA9554DB | PCA9554DB,112 | SSOP16 | Standard marking * IC's tube - DSC bulk pack | 1092 | T _{amb} = -40 °C to +85 °C |
| | PCA9554DB,118 | SSOP16 | Reel 13" Q1/T1 *standard mark SMD | 2000 | T _{amb} = -40 °C to +85 °C |

Table 2. Ordering options ...continued

| Type number | Orderable part number | Package | Packing method | Minimum order quantity | Temperature |
|----------------|-----------------------|----------|--|------------------------|-------------------------------------|
| PCA9554ADB | PCA9554ADB,112 | SSOP16 | Standard marking * IC's tube - DSC bulk pack | 1092 | T _{amb} = -40 °C to +85 °C |
| | PCA9554ADB,118 | SSOP16 | Reel 13" Q1/T1 *standard mark SMD | 2000 | T _{amb} = -40 °C to +85 °C |
| PCA9554TS | PCA9554TS,112 | SSOP20 | Standard marking * IC's tube - DSC bulk pack | 1350 | T _{amb} = -40 °C to +85 °C |
| | PCA9554TS,118 | SSOP20 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9554ATS | PCA9554ATS,112 | SSOP20 | Standard marking * IC's tube - DSC bulk pack | 1350 | T _{amb} = -40 °C to +85 °C |
| | PCA9554ATS,118 | SSOP20 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9554PW | PCA9554PW,112 | TSSOP16 | Standard marking * IC's tube - DSC bulk pack | 2400 | T _{amb} = -40 °C to +85 °C |
| | PCA9554PW,118 | TSSOP16 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9554PW/Q900 | PCA9554PW/Q900,118 | TSSOP16 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9554APW | PCA9554APW,112 | TSSOP16 | Standard marking * IC's tube - DSC bulk pack | 2400 | T _{amb} = -40 °C to +85 °C |
| | PCA9554APW,118 | TSSOP16 | Reel 13" Q1/T1 *standard mark SMD | 2500 | T _{amb} = -40 °C to +85 °C |
| PCA9554BS | PCA9554BS,118 | HVQFN16 | Reel 13" Q1/T1 *standard mark SMD | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9554ABS | PCA9554ABS,118 | HVQFN16 | Reel 13" Q1/T1 *standard mark SMD | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9554BS3 | PCA9554BS3,118 | HVQFN16 | Reel 13" Q1/T1 *standard mark SMD | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9554ABS3 | PCA9554ABS3,118 | HVQFN16 | Reel 13" Q1/T1 *standard mark SMD | 6000 | T _{amb} = -40 °C to +85 °C |
| PCA9554U | PCA9554U,029 | bare die | Reel 7" Q1/T1 *no mark die mounted on punched tape | 7000 | T _{amb} = -40 °C to +85 °C |

4. Block diagram



5. Pinning information

5.1 Pinning

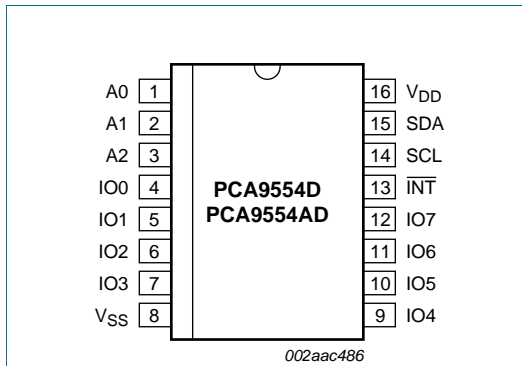


Fig 2. Pin configuration for SO16

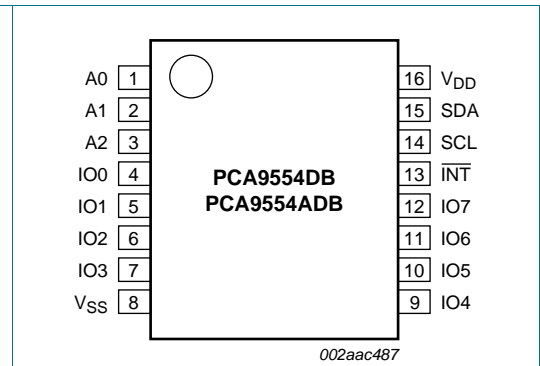


Fig 3. Pin configuration for SSOP16

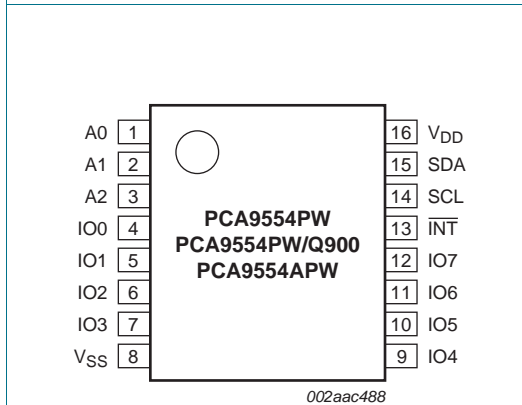


Fig 4. Pin configuration for TSSOP16

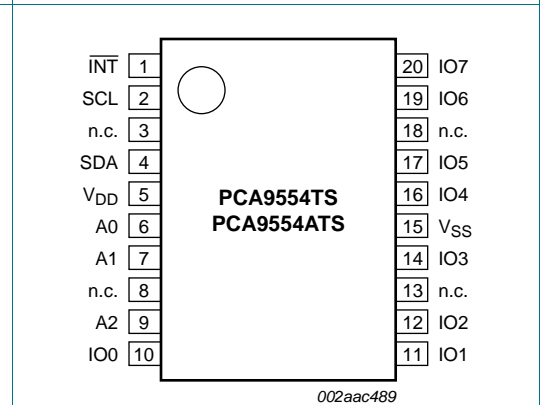


Fig 5. Pin configuration for SSOP20

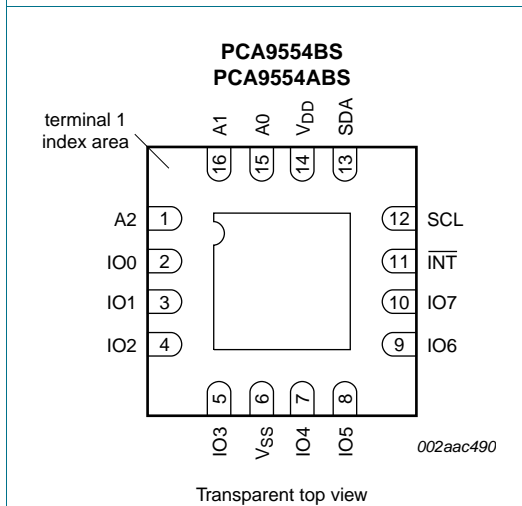


Fig 6. Pin configuration for HVQFN16 (SOT629-1)

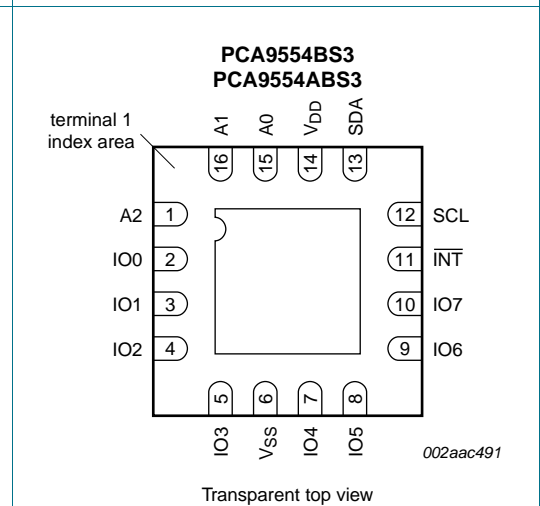


Fig 7. Pin configuration for HVQFN16 (SOT758-1)

5.2 Pin description

Table 3. Pin description

| Symbol | Pin | | | Description |
|-------------------------|-----------------------|------------------|--------------|-------------------------------|
| | SO16, SSOP16, TSSOP16 | HVQFN16 | SSOP20 | |
| A0 | 1 | 15 | 6 | address input 0 |
| A1 | 2 | 16 | 7 | address input 1 |
| A2 | 3 | 1 | 9 | address input 2 |
| IO0 | 4 | 2 | 10 | input/output 0 |
| IO1 | 5 | 3 | 11 | input/output 1 |
| IO2 | 6 | 4 | 12 | input/output 2 |
| IO3 | 7 | 5 | 14 | input/output 3 |
| V _{SS} | 8 | 6 ^[1] | 15 | supply ground |
| IO4 | 9 | 7 | 16 | input/output 4 |
| IO5 | 10 | 8 | 17 | input/output 5 |
| IO6 | 11 | 9 | 19 | input/output 6 |
| IO7 | 12 | 10 | 20 | input/output 7 |
| $\overline{\text{INT}}$ | 13 | 11 | 1 | interrupt output (open-drain) |
| SCL | 14 | 12 | 2 | serial clock line |
| SDA | 15 | 13 | 4 | serial data line |
| V _{DD} | 16 | 14 | 5 | supply voltage |
| n.c. | - | - | 3, 8, 13, 18 | not connected |

[1] HVQFN16 package die supply ground is connected to both V_{SS} pin and exposed center pad. V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board and for proper heat conduction through the board, thermal vias need to be incorporated in the PCB in the thermal pad region.

6. Functional description

Refer to [Figure 1 “Block diagram of PCA9554/PCA9554A”](#).

6.1 Registers

6.1.1 Command byte

Table 4. Command byte

| Command | Protocol | Function |
|---------|-----------------|-----------------------------|
| 0 | read byte | Input Port register |
| 1 | read/write byte | Output Port register |
| 2 | read/write byte | Polarity Inversion register |
| 3 | read/write byte | Configuration register |

The command byte is the first byte to follow the address byte during a write transmission. It is used as a pointer to determine which of the following registers will be written or read.

6.1.2 Register 0 - Input Port register

This register is a read-only port. It reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by Register 3. Writes to this register have no effect.

The default 'X' is determined by the externally applied logic level, normally '1' when no external signal externally applied because of the internal pull-up resistors.

Table 5. Register 0 - Input Port register bit description

| Bit | Symbol | Access | Value | Description |
|-----|--------|-----------|-------|--|
| 7 | I7 | read only | X | determined by externally applied logic level |
| 6 | I6 | read only | X | |
| 5 | I5 | read only | X | |
| 4 | I4 | read only | X | |
| 3 | I3 | read only | X | |
| 2 | I2 | read only | X | |
| 1 | I1 | read only | X | |
| 0 | I0 | read only | X | |

6.1.3 Register 1 - Output Port register

This register reflects the outgoing logic levels of the pins defined as outputs by Register 3. Bit values in this register have no effect on pins defined as inputs. Reads from this register return the value that is in the flip-flop controlling the output selection, **not** the actual pin value.

Table 6. Register 1 - Output Port register bit description

Legend: * default value.

| Bit | Symbol | Access | Value | Description |
|-----|--------|--------|-------|---|
| 7 | O7 | R | 1* | reflects outgoing logic levels of pins defined as outputs by Register 3 |
| 6 | O6 | R | 1* | |
| 5 | O5 | R | 1* | |
| 4 | O4 | R | 1* | |
| 3 | O3 | R | 1* | |
| 2 | O2 | R | 1* | |
| 1 | O1 | R | 1* | |
| 0 | O0 | R | 1* | |

6.1.4 Register 2 - Polarity Inversion register

This register allows the user to invert the polarity of the Input Port register data. If a bit in this register is set (written with '1'), the corresponding Input Port data is inverted. If a bit in this register is cleared (written with a '0'), the Input Port data polarity is retained.

Table 7. Register 2 - Polarity Inversion register bit description

Legend: * default value.

| Bit | Symbol | Access | Value | Description |
|-----|--------|--------|-------|--|
| 7 | N7 | R/W | 0* | inverts polarity of Input Port register data 0 = Input Port register data retained (default value) 1 = Input Port register data inverted |
| 6 | N6 | R/W | 0* | |
| 5 | N5 | R/W | 0* | |
| 4 | N4 | R/W | 0* | |
| 3 | N3 | R/W | 0* | |
| 2 | N2 | R/W | 0* | |
| 1 | N1 | R/W | 0* | |
| 0 | N0 | R/W | 0* | |

6.1.5 Register 3 - Configuration register

This register configures the directions of the I/O pins. If a bit in this register is set, the corresponding port pin is enabled as an input with high-impedance output driver. If a bit in this register is cleared, the corresponding port pin is enabled as an output. At reset, the I/Os are configured as inputs with a weak pull-up to V_{DD}.

Table 8. Register 3 - Configuration register bit description

Legend: * default value.

| Bit | Symbol | Access | Value | Description |
|-----|--------|--------|-------|--|
| 7 | C7 | R/W | 1* | configures the directions of the I/O pins 0 = corresponding port pin enabled as an output 1 = corresponding port pin configured as input (default value) |
| 6 | C6 | R/W | 1* | |
| 5 | C5 | R/W | 1* | |
| 4 | C4 | R/W | 1* | |
| 3 | C3 | R/W | 1* | |
| 2 | C2 | R/W | 1* | |
| 1 | C1 | R/W | 1* | |
| 0 | C0 | R/W | 1* | |

6.2 Power-on reset

When power is applied to V_{DD}, an internal Power-On Reset (POR) holds the PCA9554/PCA9554A in a reset condition until V_{DD} has reached V_{POR}. At that point, the reset condition is released and the PCA9554/PCA9554A registers and state machine will initialize to their default states. Thereafter, V_{DD} must be lowered below 0.2 V to reset the device.

For a power reset cycle, V_{DD} must be lowered below 0.2 V and then restored to the operating voltage.

6.3 Interrupt output

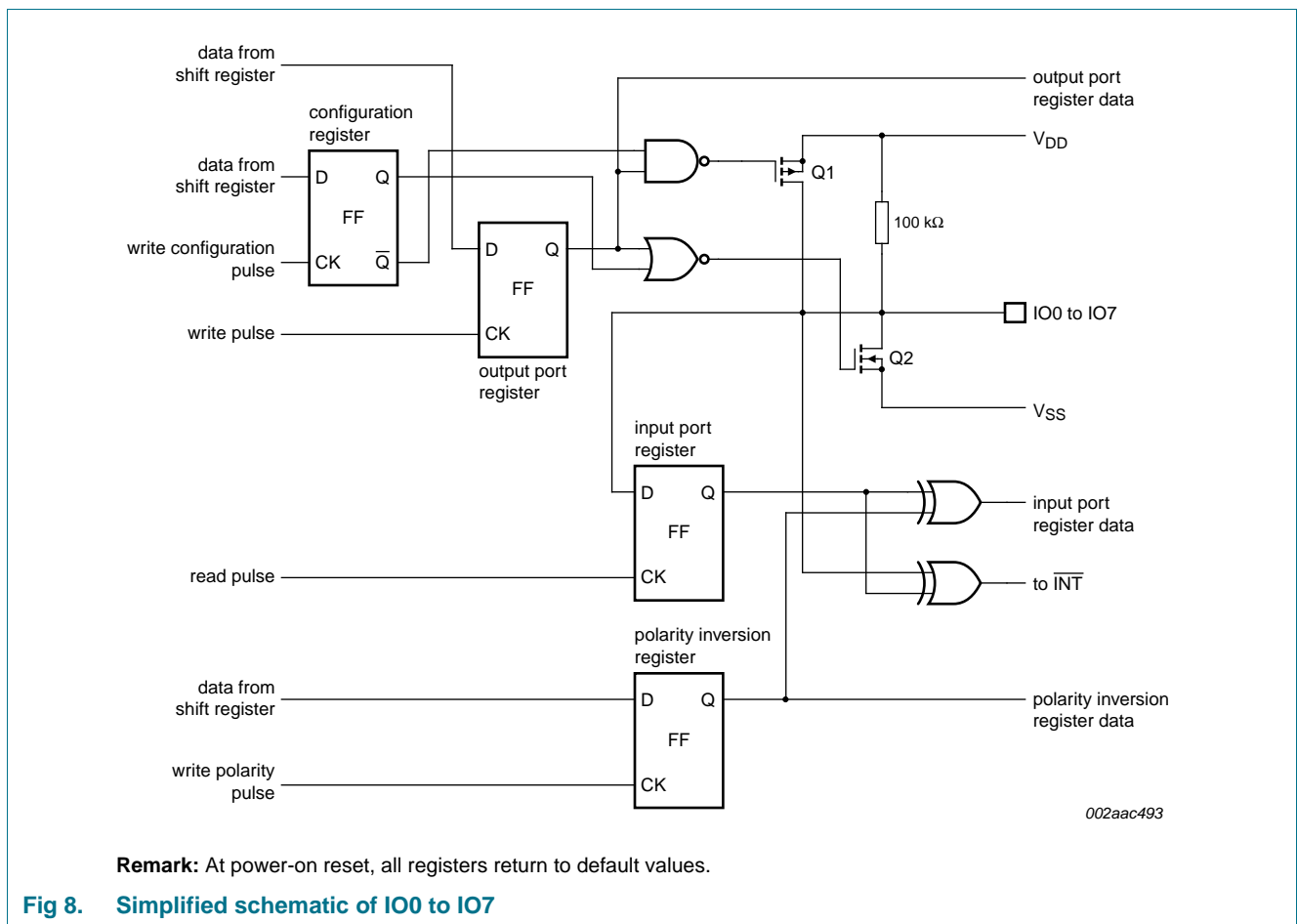
The open-drain interrupt output is activated when one of the port pins change state and the pin is configured as an input. The interrupt is deactivated when the input returns to its previous state or the Input Port register is read.

Note that changing an I/O from and output to an input may cause a false interrupt to occur if the state of the pin does not match the contents of the Input Port register.

6.4 I/O port

When an I/O is configured as an input, FETs Q1 and Q2 are off, creating a high-impedance input with a weak pull-up (100 kΩ typ.) to V_{DD}. The input voltage may be raised above V_{DD} to a maximum of 5.5 V.

If the I/O is configured as an output, then either Q1 or Q2 is enabled, depending on the state of the Output Port register. Care should be exercised if an external voltage is applied to an I/O configured as an output because of the low-impedance paths that exist between the pin and either V_{DD} or V_{SS}.



6.5 Device address

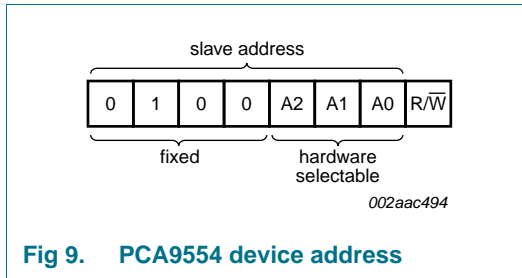


Fig 9. PCA9554 device address

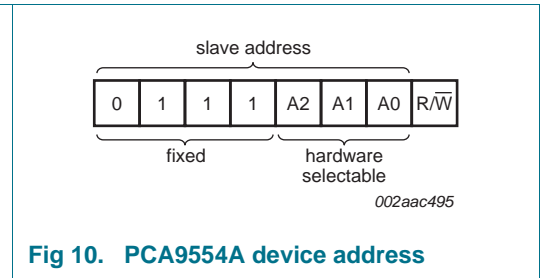


Fig 10. PCA9554A device address

6.6 Bus transactions

Data is transmitted to the PCA9554/PCA9554A registers using the Write mode as shown in Figure 11 and Figure 12. Data is read from the PCA9554/PCA9554A registers using the Read mode as shown in Figure 13 and Figure 14. These devices do not implement an auto-increment function, so once a command byte has been sent, the register which was addressed will continue to be accessed by reads until a new command byte has been sent.

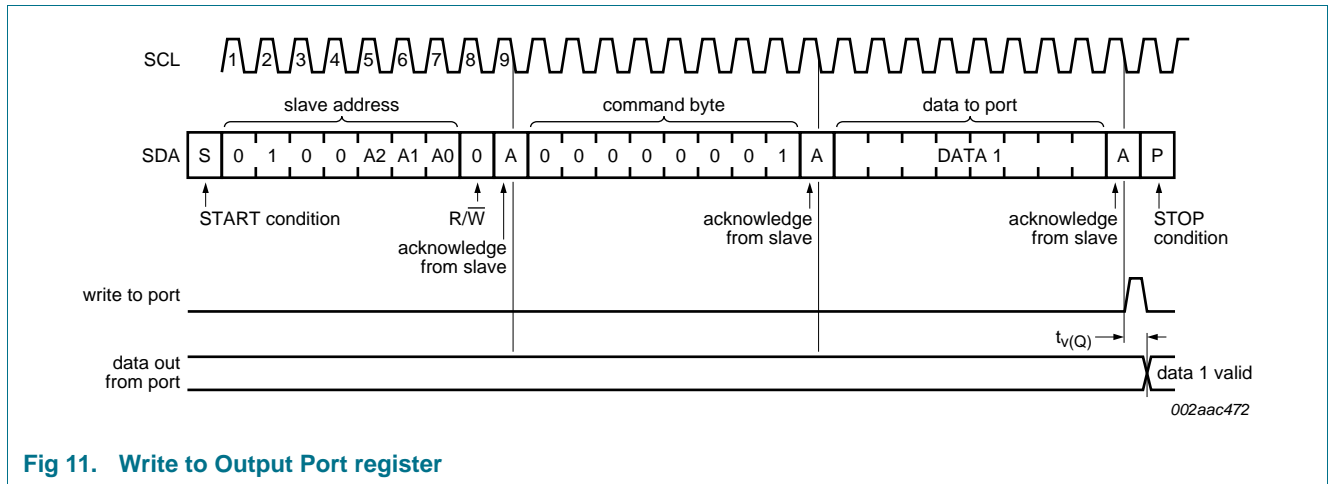


Fig 11. Write to Output Port register

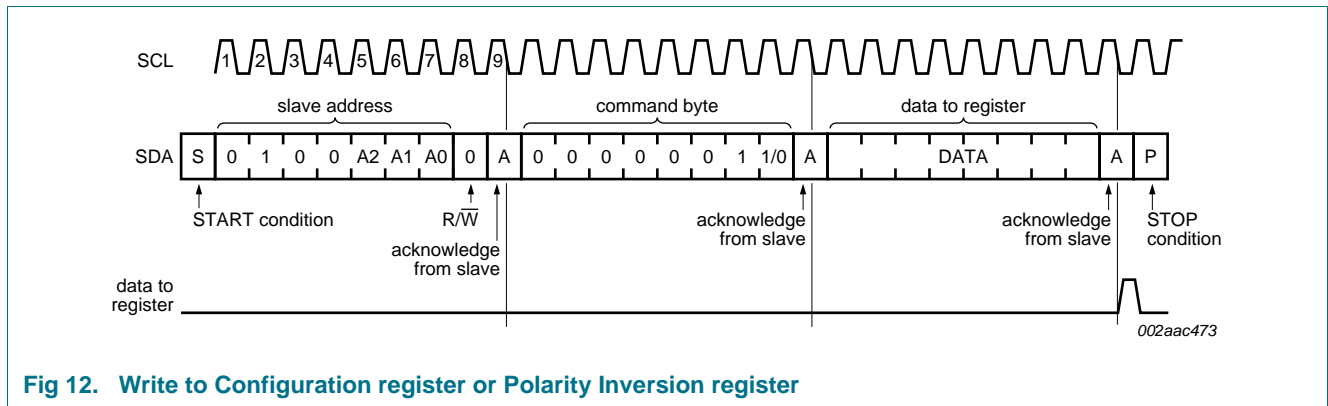


Fig 12. Write to Configuration register or Polarity Inversion register

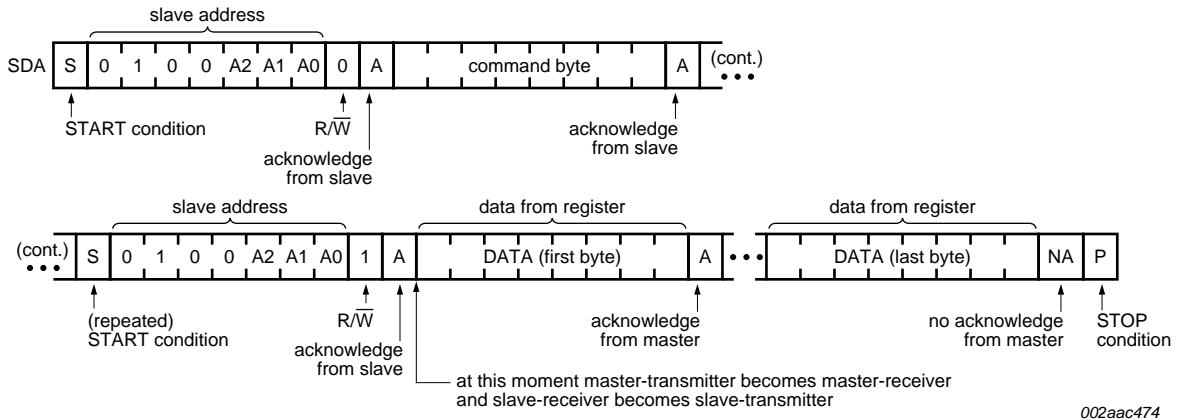
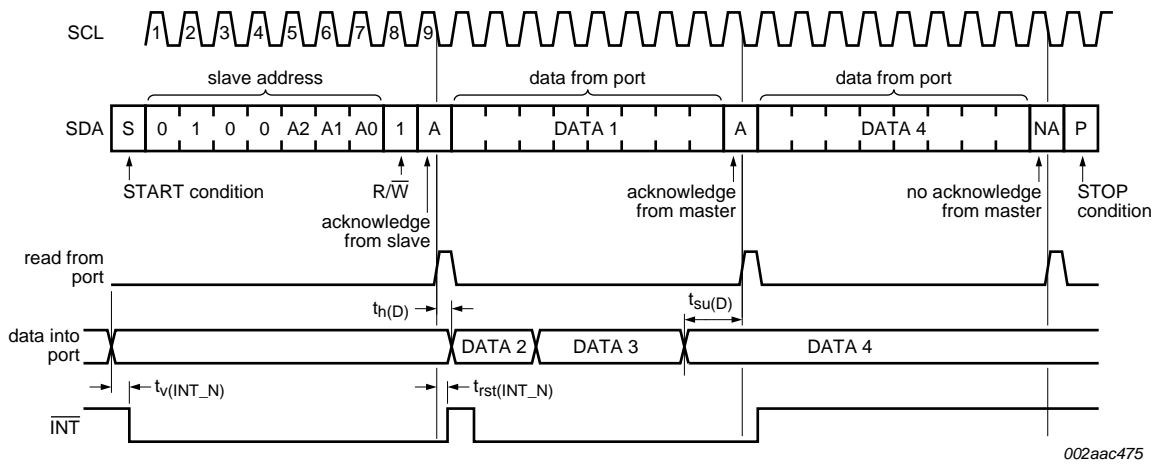


Fig 13. Read from register



This figure assumes the command byte has previously been programmed with 00h.
 Transfer of data can be stopped at any moment by a STOP condition.

Fig 14. Read Input Port register

7. Application design-in information

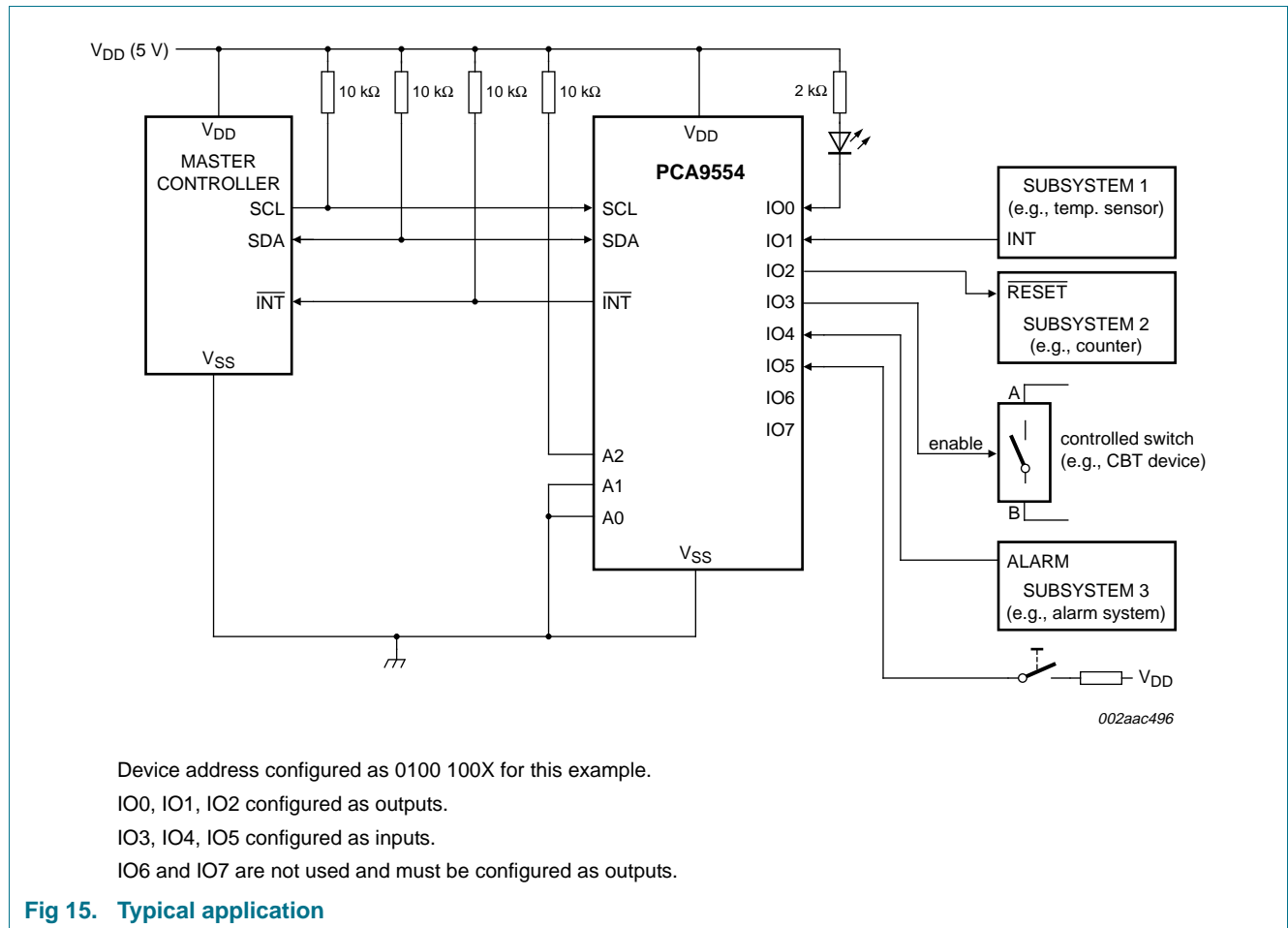


Fig 15. Typical application

8. Limiting values

Table 9. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|---------------------|---------------------------------------|------------|-----------------------|------|------|
| V _{DD} | supply voltage | | -0.5 | +6.0 | V |
| I _I | input current | | - | ±20 | mA |
| V _{I/O} | voltage on an input/output pin | | V _{SS} - 0.5 | 5.5 | V |
| I _{O(IOn)} | output current on pin IO _n | | - | ±50 | mA |
| I _{DD} | supply current | | - | 85 | mA |
| I _{SS} | ground supply current | | - | 100 | mA |
| P _{tot} | total power dissipation | | - | 200 | mW |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| T _{amb} | ambient temperature | operating | -40 | +85 | °C |

9. Static characteristics

Table 10. Static characteristics
 $V_{DD} = 2.3 \text{ V to } 5.5 \text{ V}; V_{SS} = 0 \text{ V}; T_{amb} = -40 \text{ }^{\circ}\text{C to } +85 \text{ }^{\circ}\text{C};$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | |
|------------------------------------|---------------------------|---|--------------|------|---------------|---------------|----|
| Supplies | | | | | | | |
| V_{DD} | supply voltage | | 2.3 | - | 5.5 | V | |
| I_{DD} | supply current | operating mode; $V_{DD} = 5.5 \text{ V};$ no load; $f_{SCL} = 100 \text{ kHz}$ | - | 104 | 175 | μA | |
| I_{stb} | standby current | Standby mode; $V_{DD} = 5.5 \text{ V};$ no load; $V_I = V_{SS}; f_{SCL} = 0 \text{ kHz};$ I/O = inputs | - | 550 | 700 | μA | |
| | | Standby mode; $V_{DD} = 5.5 \text{ V};$ no load; $V_I = V_{DD}; f_{SCL} = 0 \text{ kHz};$ I/O = inputs | - | 0.25 | 1 | μA | |
| V_{POR} | power-on reset voltage | no load; $V_I = V_{DD}$ or V_{SS} | [1] | 1.7 | 2.2 | V | |
| Input SCL; input/output SDA | | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | +0.3 V_{DD} | V | |
| V_{IH} | HIGH-level input voltage | | 0.7 V_{DD} | - | 5.5 | V | |
| I_{OL} | LOW-level output current | $V_{OL} = 0.4 \text{ V}$ | 3 | 6 | - | mA | |
| I_L | leakage current | $V_I = V_{DD} = V_{SS}$ | -1 | - | +1 | μA | |
| C_i | input capacitance | $V_I = V_{SS}$ | - | 6 | 10 | pF | |
| I/Os | | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | +0.8 | V | |
| V_{IH} | HIGH-level input voltage | | 2.0 | - | 5.5 | V | |
| I_{OL} | LOW-level output current | $V_{OL} = 0.5 \text{ V}; V_{DD} = 2.3 \text{ V}$ | [2] | 8 | 10 | - | mA |
| | | $V_{OL} = 0.7 \text{ V}; V_{DD} = 2.3 \text{ V}$ | [2] | 10 | 13 | - | mA |
| | | $V_{OL} = 0.5 \text{ V}; V_{DD} = 3.0 \text{ V}$ | [2] | 8 | 14 | - | mA |
| | | $V_{OL} = 0.7 \text{ V}; V_{DD} = 3.0 \text{ V}$ | [2] | 10 | 19 | - | mA |
| | | $V_{OL} = 0.5 \text{ V}; V_{DD} = 4.5 \text{ V}$ | [2] | 8 | 17 | - | mA |
| | | $V_{OL} = 0.7 \text{ V}; V_{DD} = 4.5 \text{ V}$ | [2] | 10 | 24 | - | mA |
| V_{OH} | HIGH-level output voltage | $I_{OH} = -8 \text{ mA}; V_{DD} = 2.3 \text{ V}$ | [3] | 1.8 | - | - | V |
| | | $I_{OH} = -10 \text{ mA}; V_{DD} = 2.3 \text{ V}$ | [3] | 1.7 | - | - | V |
| | | $I_{OH} = -8 \text{ mA}; V_{DD} = 3.0 \text{ V}$ | [3] | 2.6 | - | - | V |
| | | $I_{OH} = -10 \text{ mA}; V_{DD} = 3.0 \text{ V}$ | [3] | 2.5 | - | - | V |
| | | $I_{OH} = -8 \text{ mA}; V_{DD} = 4.75 \text{ V}$ | [3] | 4.1 | - | - | V |
| | | $I_{OH} = -10 \text{ mA}; V_{DD} = 4.75 \text{ V}$ | [3] | 4.0 | - | - | V |
| I_{LI} | input leakage current | $V_{DD} = 3.6 \text{ V}; V_I = V_{DD}$ | -1 | - | +1 | μA | |
| I_L | leakage current | $V_{DD} = 5.5 \text{ V}; V_I = V_{SS}$ | - | - | -100 | μA | |
| C_i | input capacitance | | - | 3.7 | 5 | pF | |
| C_o | output capacitance | | - | 3.7 | 5 | pF | |
| Interrupt INT | | | | | | | |
| I_{OL} | LOW-level output current | $V_{OL} = 0.4 \text{ V}$ | 3 | - | - | mA | |

Table 10. Static characteristics ...continued

$V_{DD} = 2.3\text{ V to }5.5\text{ V}$; $V_{SS} = 0\text{ V}$; $T_{amb} = -40\text{ °C to }+85\text{ °C}$; unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---------------------------------|--------------------------|------------|------|-----|-----|---------------|
| Select inputs A0, A1, A2 | | | | | | |
| V_{IL} | LOW-level input voltage | | -0.5 | - | 0.8 | V |
| V_{IH} | HIGH-level input voltage | | 2.0 | - | 5.5 | V |
| I_{LI} | input leakage current | | -1 | - | 1 | μA |

[1] V_{DD} must be lowered to 0.2 V for at least 5 μs in order to reset part.

[2] Each I/O must be externally limited to a maximum of 25 mA and the device must be limited to a maximum current of 100 mA.

[3] The total current sourced by all I/Os must be limited to 85 mA.

10. Dynamic characteristics

Table 11. Dynamic characteristics

| Symbol | Parameter | Conditions | Standard-mode I ² C-bus | | Fast-mode I ² C-bus | | Unit |
|-------------------------|---|------------|------------------------------------|------|--------------------------------|-----|---------------|
| | | | Min | Max | Min | Max | |
| f_{SCL} | SCL clock frequency | | 0 | 100 | 0 | 400 | kHz |
| t_{BUF} | bus free time between a STOP and START condition | | 4.7 | - | 1.3 | - | μs |
| $t_{HD;STA}$ | hold time (repeated) START condition | | 4.0 | - | 0.6 | - | μs |
| $t_{SU;STA}$ | set-up time for a repeated START condition | | 4.7 | - | 0.6 | - | μs |
| $t_{SU;STO}$ | set-up time for STOP condition | | 4.0 | - | 0.6 | - | μs |
| $t_{HD;DAT}$ | data hold time | | 0 | - | 0 | - | μs |
| $t_{VD;ACK}$ | data valid acknowledge time | [1] | 0.3 | 3.45 | 0.1 | 0.9 | μs |
| $t_{VD;DAT}$ | data valid time | [2] | 300 | - | 50 | - | ns |
| $t_{SU;DAT}$ | data set-up time | | 250 | - | 100 | - | ns |
| t_{LOW} | LOW period of the SCL clock | | 4.7 | - | 1.3 | - | μs |
| t_{HIGH} | HIGH period of the SCL clock | | 4.0 | - | 0.6 | - | μs |
| t_r | rise time of both SDA and SCL signals | | - | 1000 | $20 + 0.1C_b$ [3] | 300 | ns |
| t_f | fall time of both SDA and SCL signals | | - | 300 | $20 + 0.1C_b$ [3] | 300 | ns |
| t_{SP} | pulse width of spikes that must be suppressed by the input filter | | - | 50 | - | 50 | ns |
| Port timing | | | | | | | |
| $t_{V(Q)}$ | data output valid time | | - | 200 | - | 200 | ns |
| $t_{su(D)}$ | data input set-up time | | 100 | - | 100 | - | ns |
| $t_{h(D)}$ | data input hold time | | 1 | - | 1 | - | μs |
| Interrupt timing | | | | | | | |
| $t_{V(INT_N)}$ | valid time on pin \overline{INT} | | - | 4 | - | 4 | μs |
| $t_{rst(INT_N)}$ | reset time on pin \overline{INT} | | - | 4 | - | 4 | μs |

[1] $t_{VD;ACK}$ = time for Acknowledgement signal from SCL LOW to SDA (out) LOW.

[2] $t_{VD;DAT}$ = minimum time for SDA data output to be valid following SCL LOW.

[3] C_b = total capacitance of one bus line in pF.

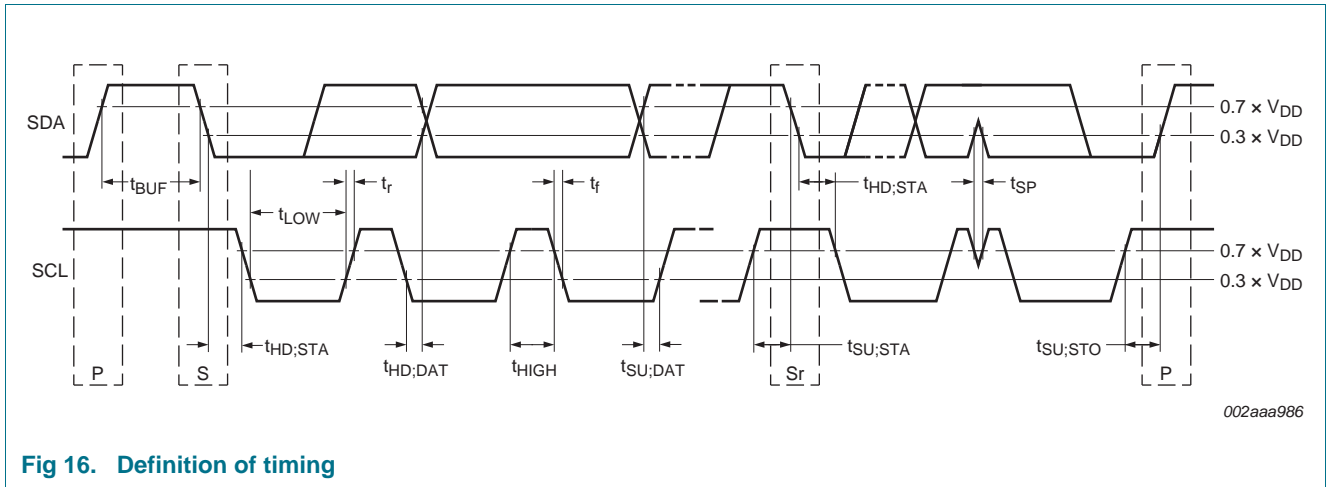


Fig 16. Definition of timing

11. Package outline

SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1

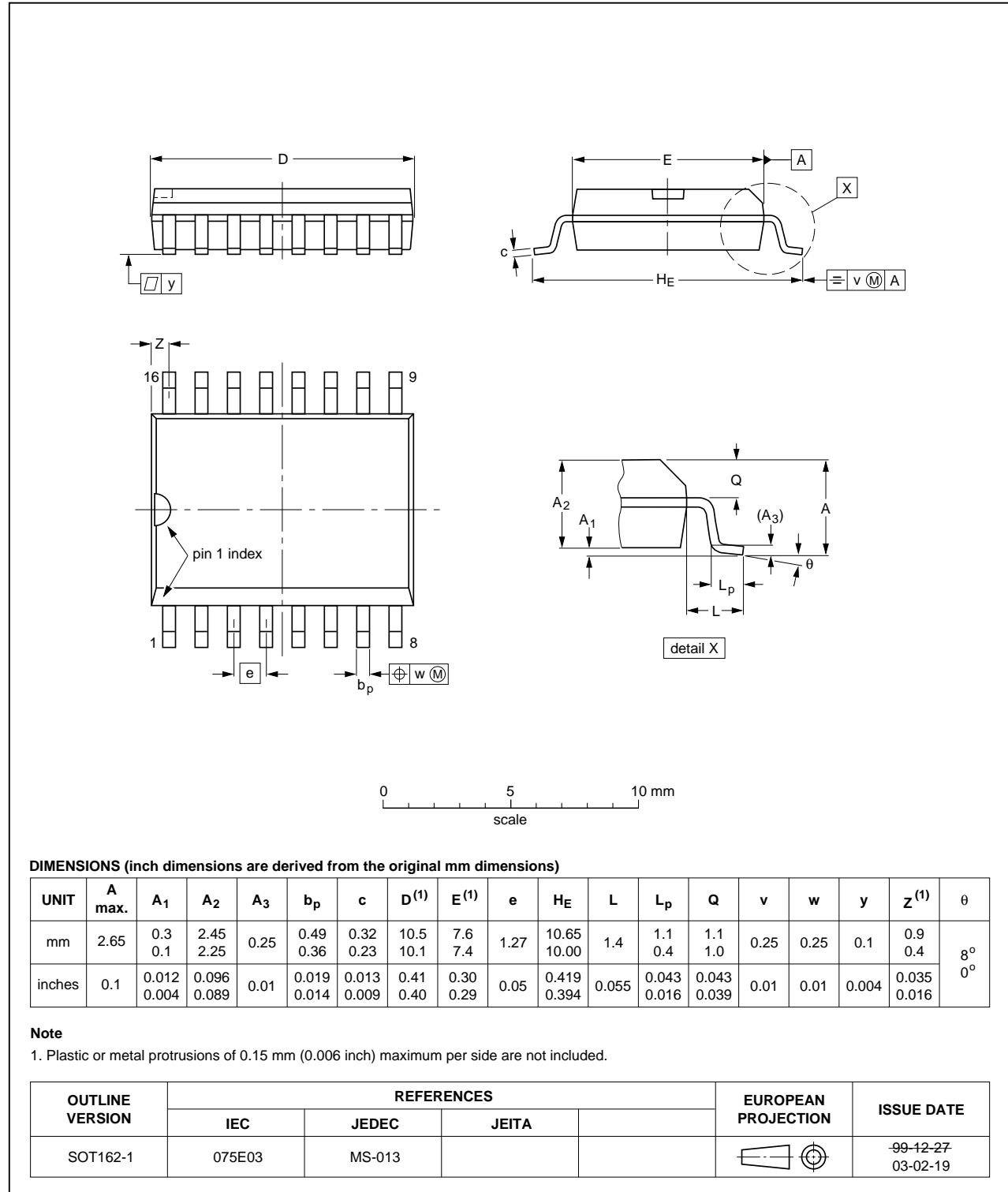


Fig 17. Package outline SOT162-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

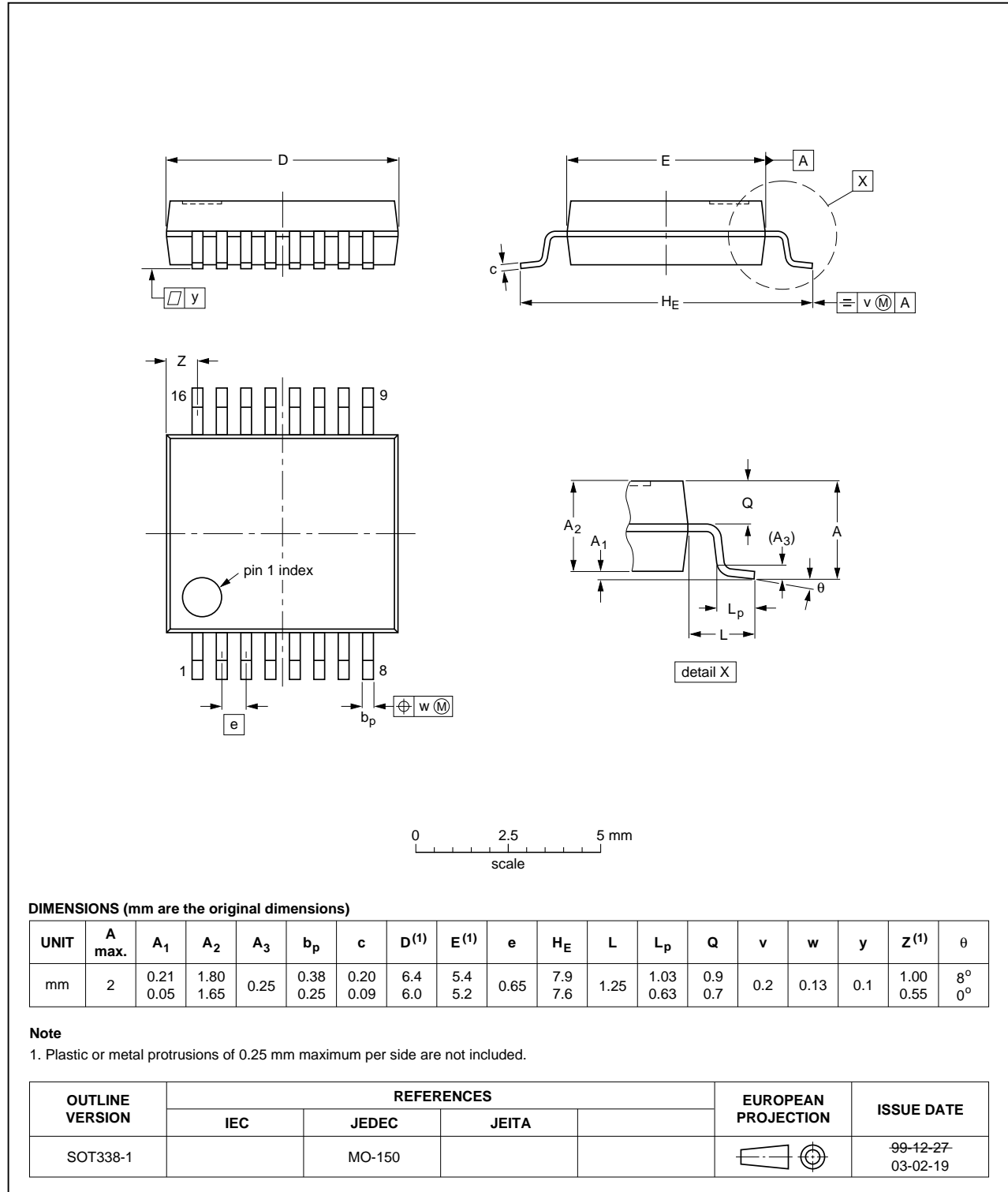


Fig 18. Package outline SOT338-1 (SSOP16)

SSOP20: plastic shrink small outline package; 20 leads; body width 4.4 mm

SOT266-1

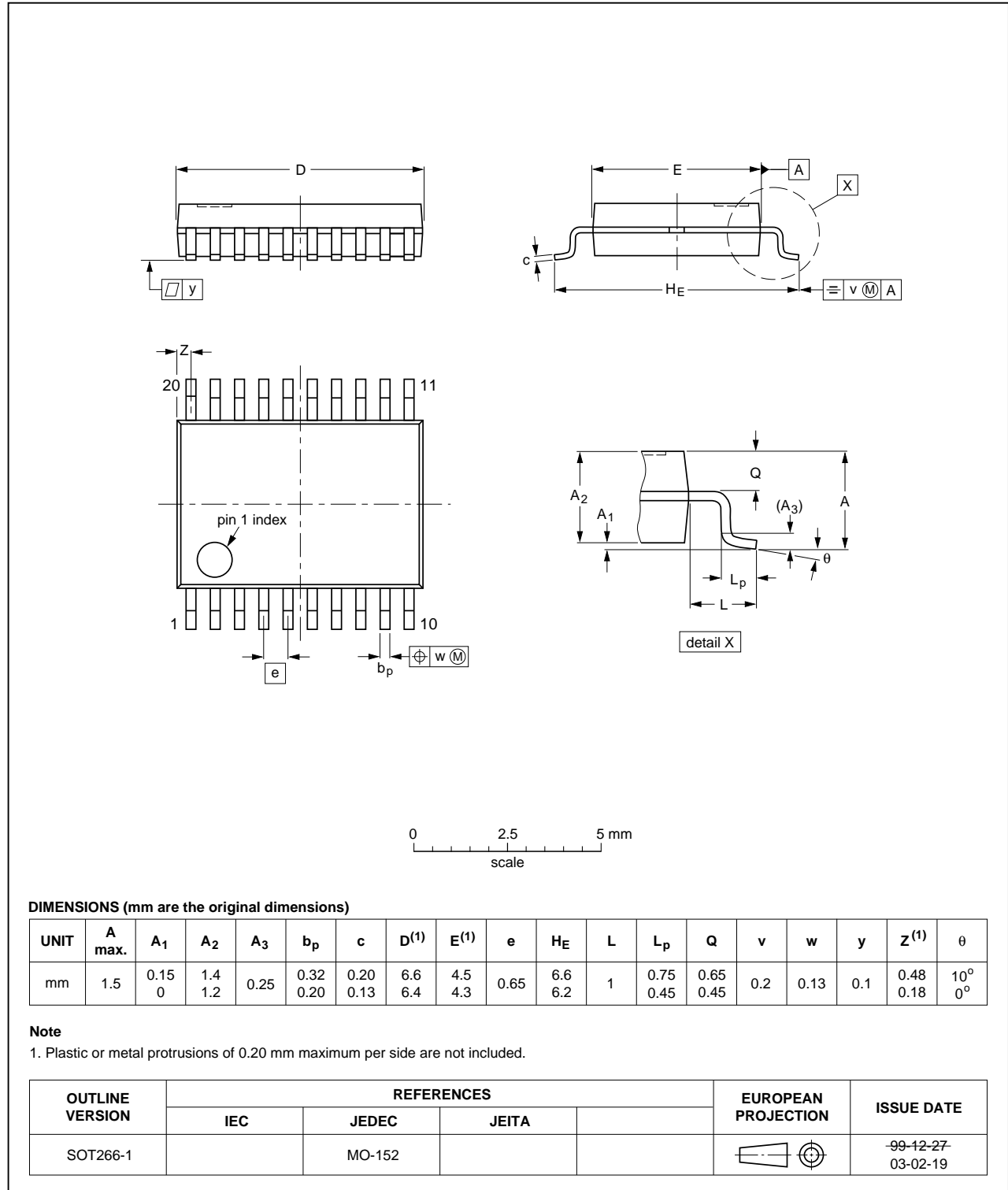


Fig 19. Package outline SOT266-1 (SSOP20)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

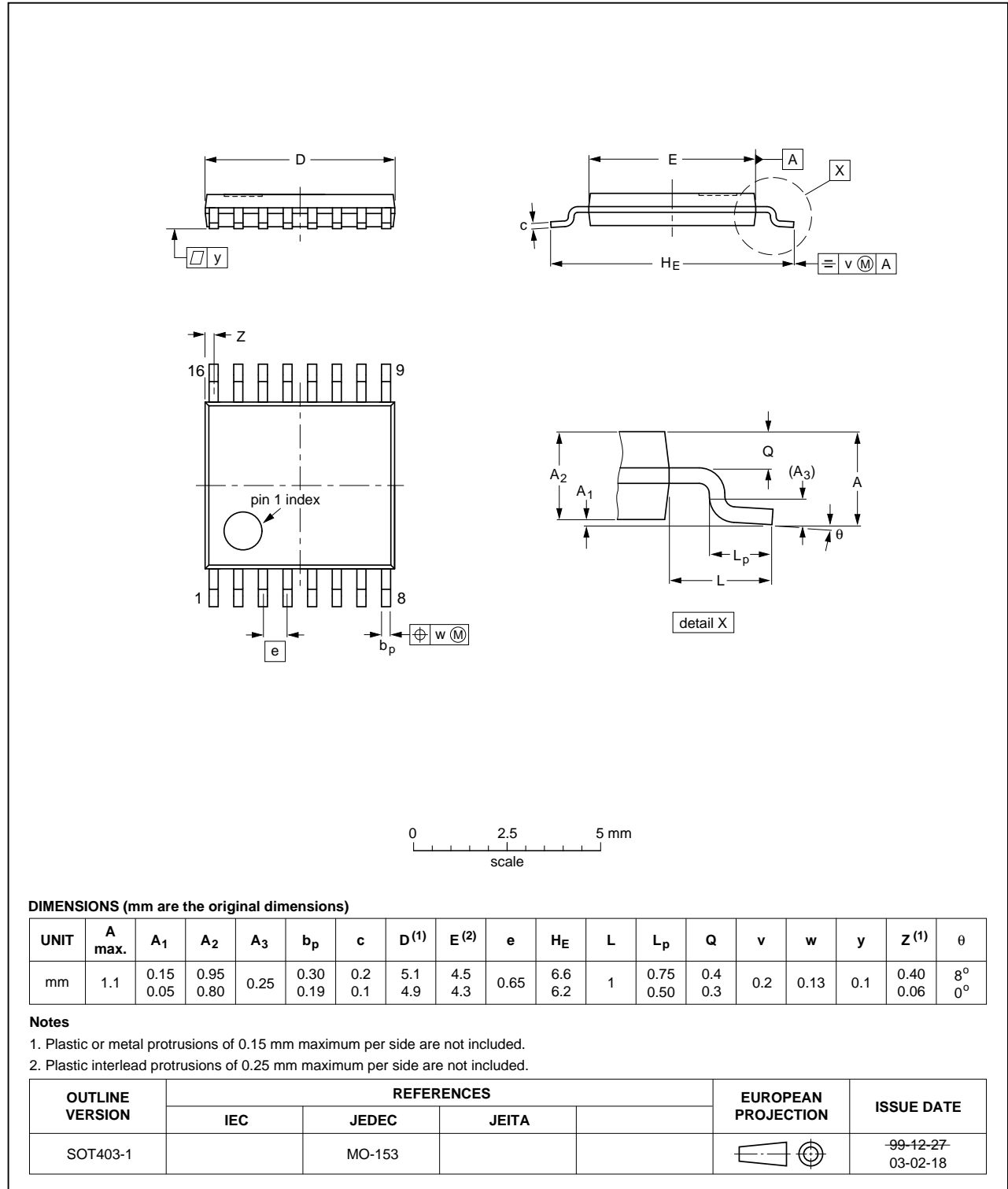


Fig 20. Package outline SOT403-1 (TSSOP16)

HVQFN16: plastic thermal enhanced very thin quad flat package; no leads;
16 terminals; body 4 x 4 x 0.85 mm

SOT629-1

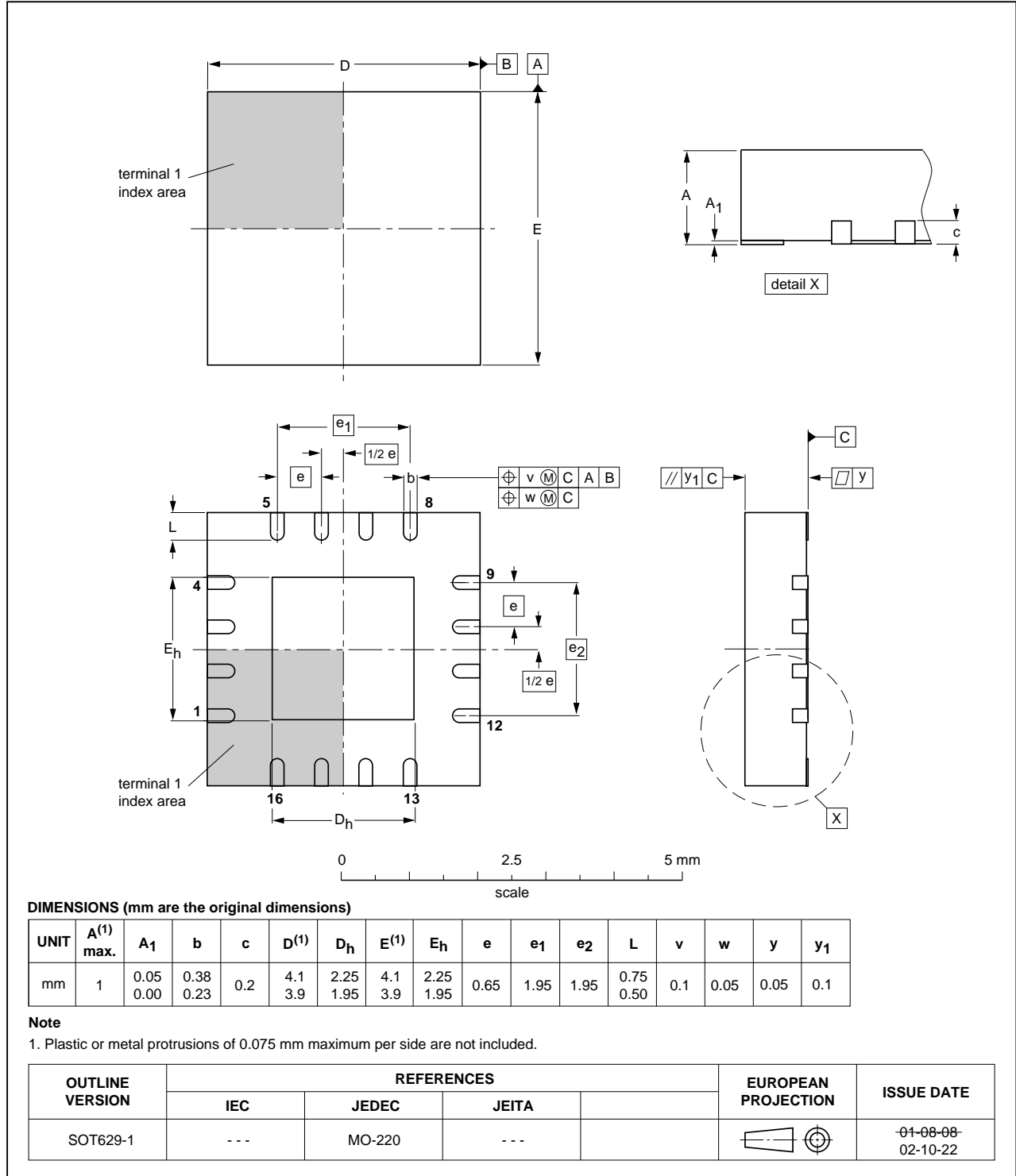


Fig 21. Package outline SOT629-1 (HVQFN16)

HVQFN16: plastic thermal enhanced very thin quad flat package; no leads;
16 terminals; body 3 x 3 x 0.85 mm

SOT758-1

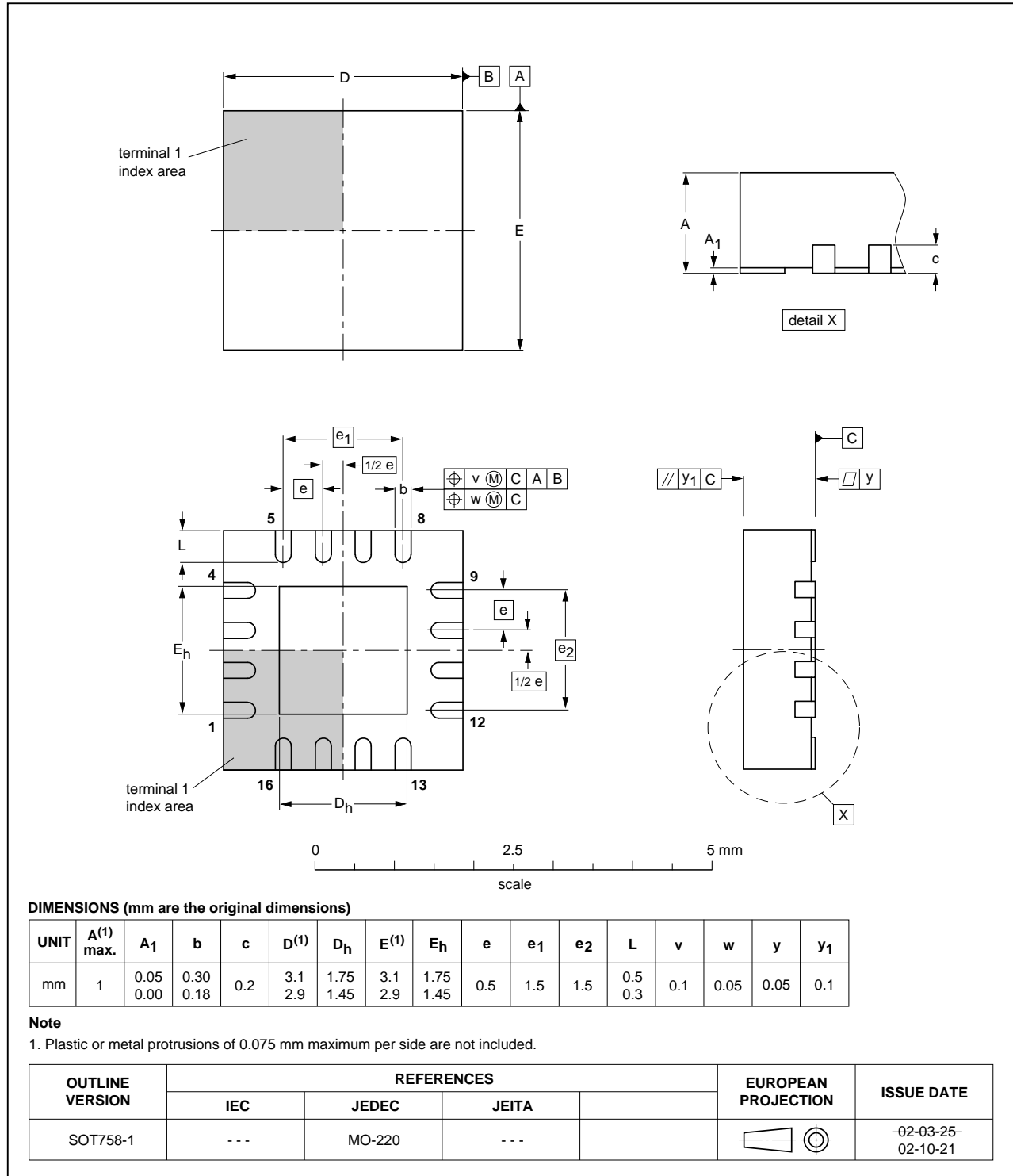


Fig 22. Package outline SOT758-1 (HVQFN16)

12. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

13. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

13.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

13.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

13.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

13.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 23](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 12](#) and [13](#)

Table 12. SnPb eutectic process (from J-STD-020C)

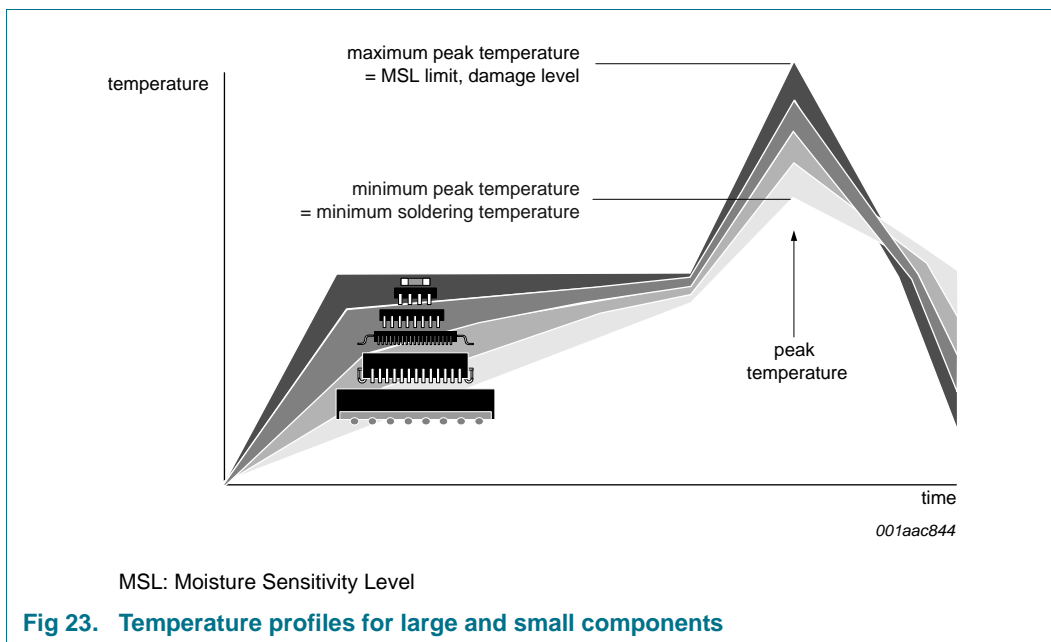
| Package thickness (mm) | Package reflow temperature (°C) | |
|------------------------|---------------------------------|-------|
| | Volume (mm ³) | |
| | < 350 | ≥ 350 |
| < 2.5 | 235 | 220 |
| ≥ 2.5 | 220 | 220 |

Table 13. Lead-free process (from J-STD-020C)

| Package thickness (mm) | Package reflow temperature (°C) | | |
|------------------------|---------------------------------|-------------|--------|
| | Volume (mm ³) | | |
| | < 350 | 350 to 2000 | > 2000 |
| < 1.6 | 260 | 260 | 260 |
| 1.6 to 2.5 | 260 | 250 | 245 |
| > 2.5 | 250 | 245 | 245 |

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 23](#).

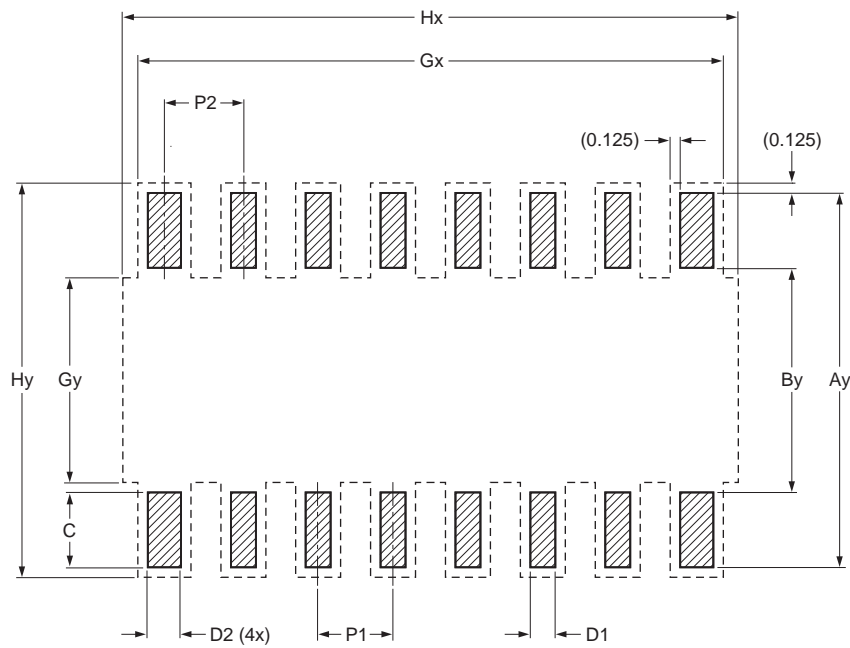


For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.

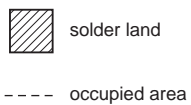
14. Soldering: PCB footprints

Footprint information for reflow soldering of SO16 package

SOT162-1



Generic footprint pattern
Refer to the package outline drawing for actual layout



DIMENSIONS in mm

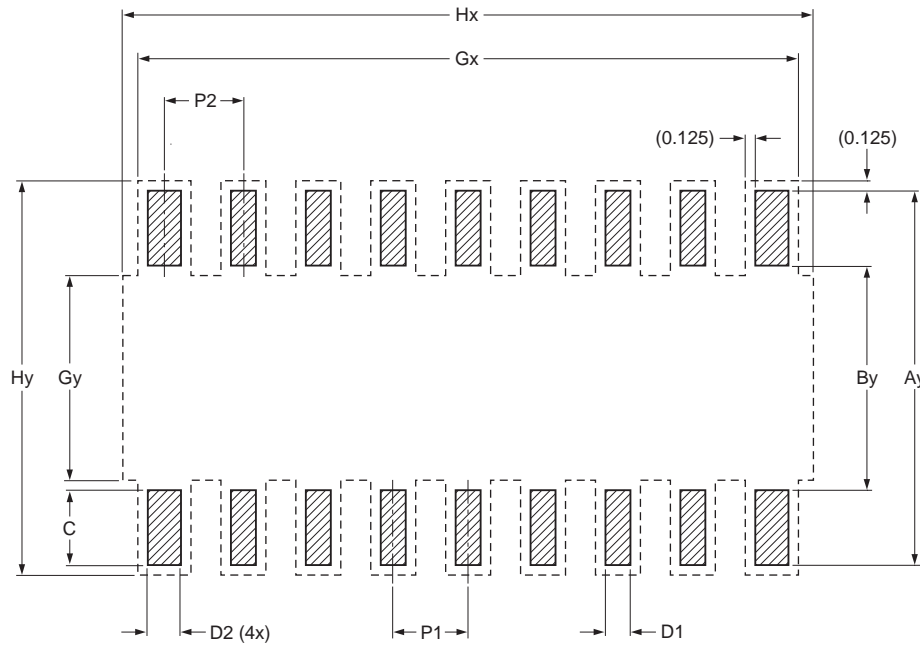
| P1 | P2 | Ay | By | C | D1 | D2 | Gx | Gy | Hx | Hy |
|-------|-------|--------|-------|-------|-------|-------|--------|-------|--------|--------|
| 1.270 | 1.320 | 11.200 | 6.400 | 2.400 | 0.700 | 0.800 | 10.040 | 8.600 | 11.900 | 11.450 |

sot162-1_fr

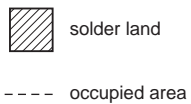
Fig 24. PCB footprint for SOT162-1 (SO16); reflow soldering

Footprint information for reflow soldering of SSOP16 package

SOT338-1



Generic footprint pattern
Refer to the package outline drawing for actual layout



DIMENSIONS in mm

| P1 | P2 | Ay | By | C | D1 | D2 | Gx | Gy | Hx | Hy |
|------|------|-----|-----|-----|-----|-----|-----|-----|-----|------|
| 0.65 | 0.75 | 8.6 | 5.4 | 1.6 | 0.4 | 0.6 | 5.6 | 6.1 | 7.0 | 8.85 |

Issue date ~~09-02-22~~
15-03-26

sot338-1_fr

Fig 25. PCB footprint for SOT338-1 (HVQFN16); reflow soldering

Footprint information for reflow soldering of SSOP20 package

SOT266-1

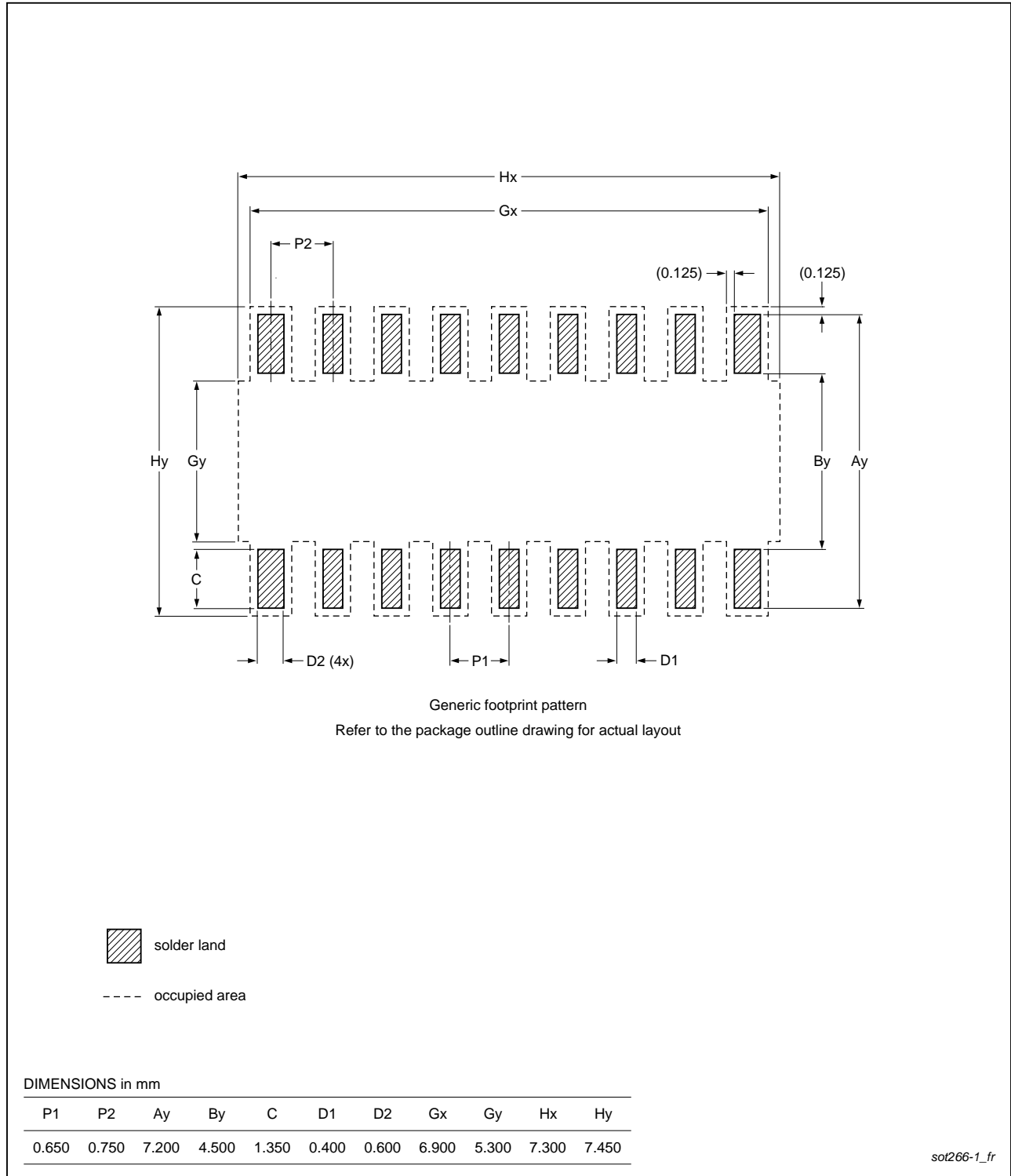


Fig 26. PCB footprint for SOT266-1 (SSOP20); reflow soldering

Footprint information for reflow soldering of TSSOP16 package

SOT403-1

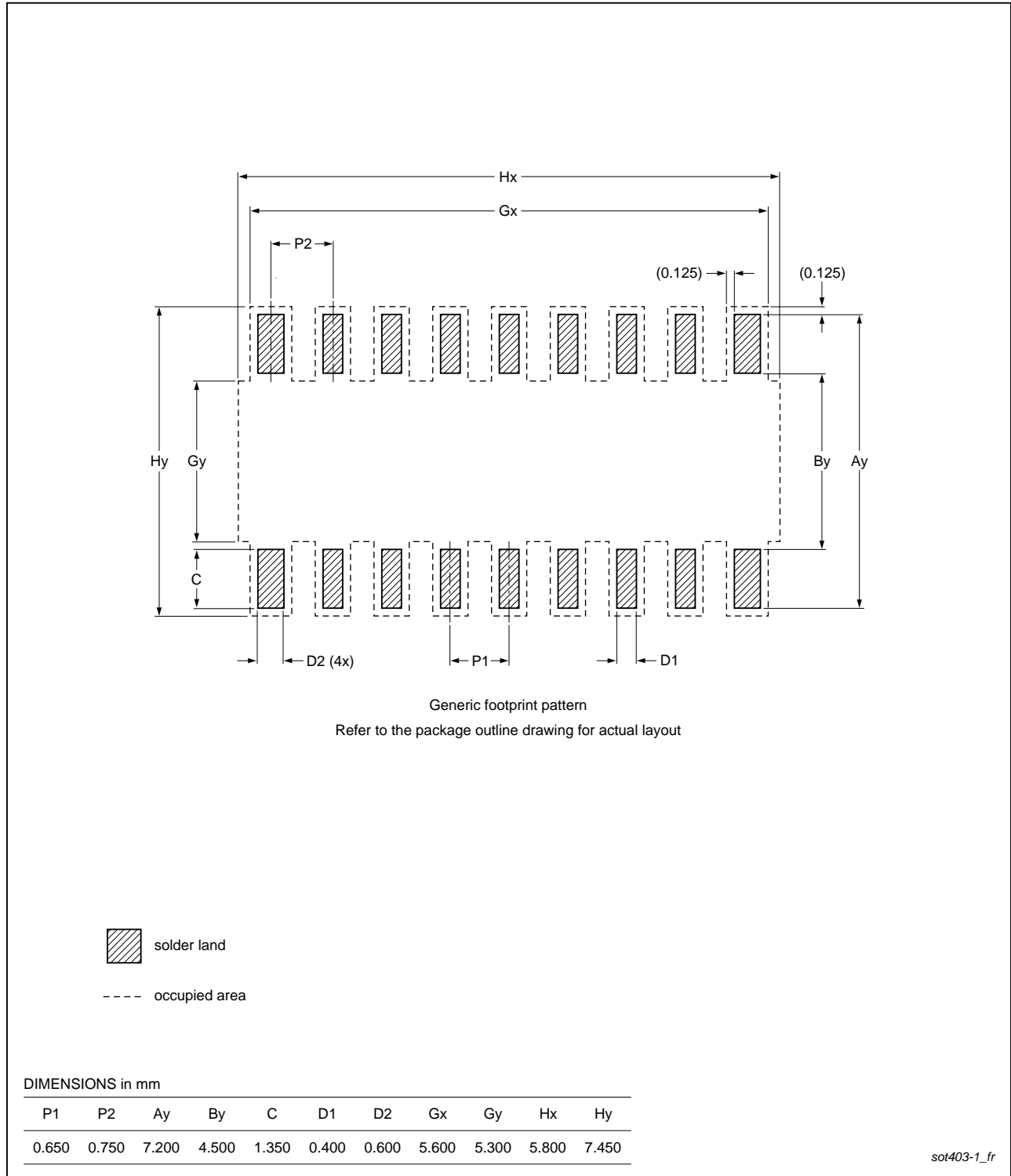


Fig 27. PCB footprint for SOT403-1 (TSSOP16); reflow soldering

Footprint information for reflow soldering of HVQFN16 package

SOT629-1

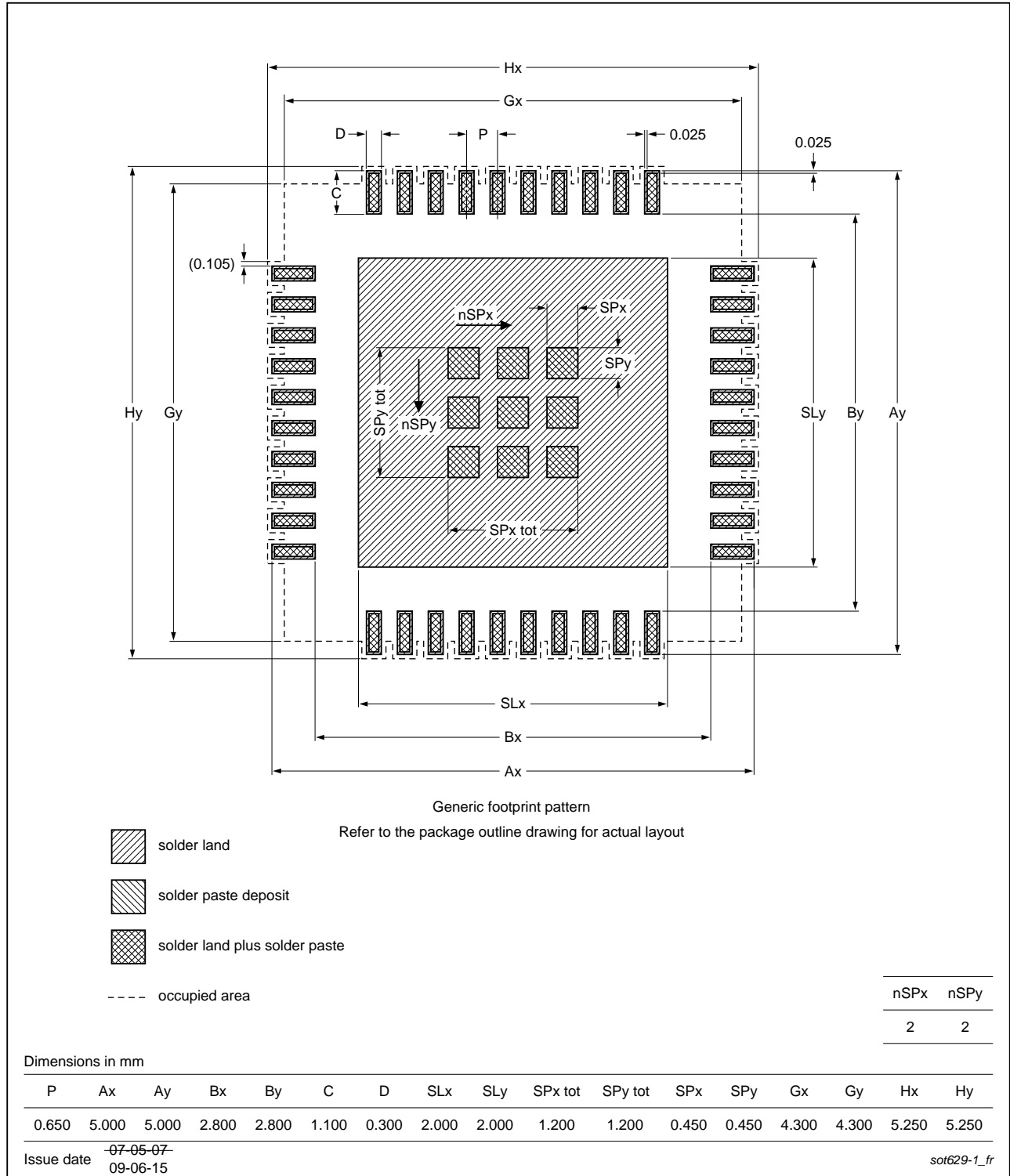


Fig 28. PCB footprint for SOT629-1 (HVQFN16); reflow soldering

Footprint information for reflow soldering of HVQFN16 package

SOT758-1

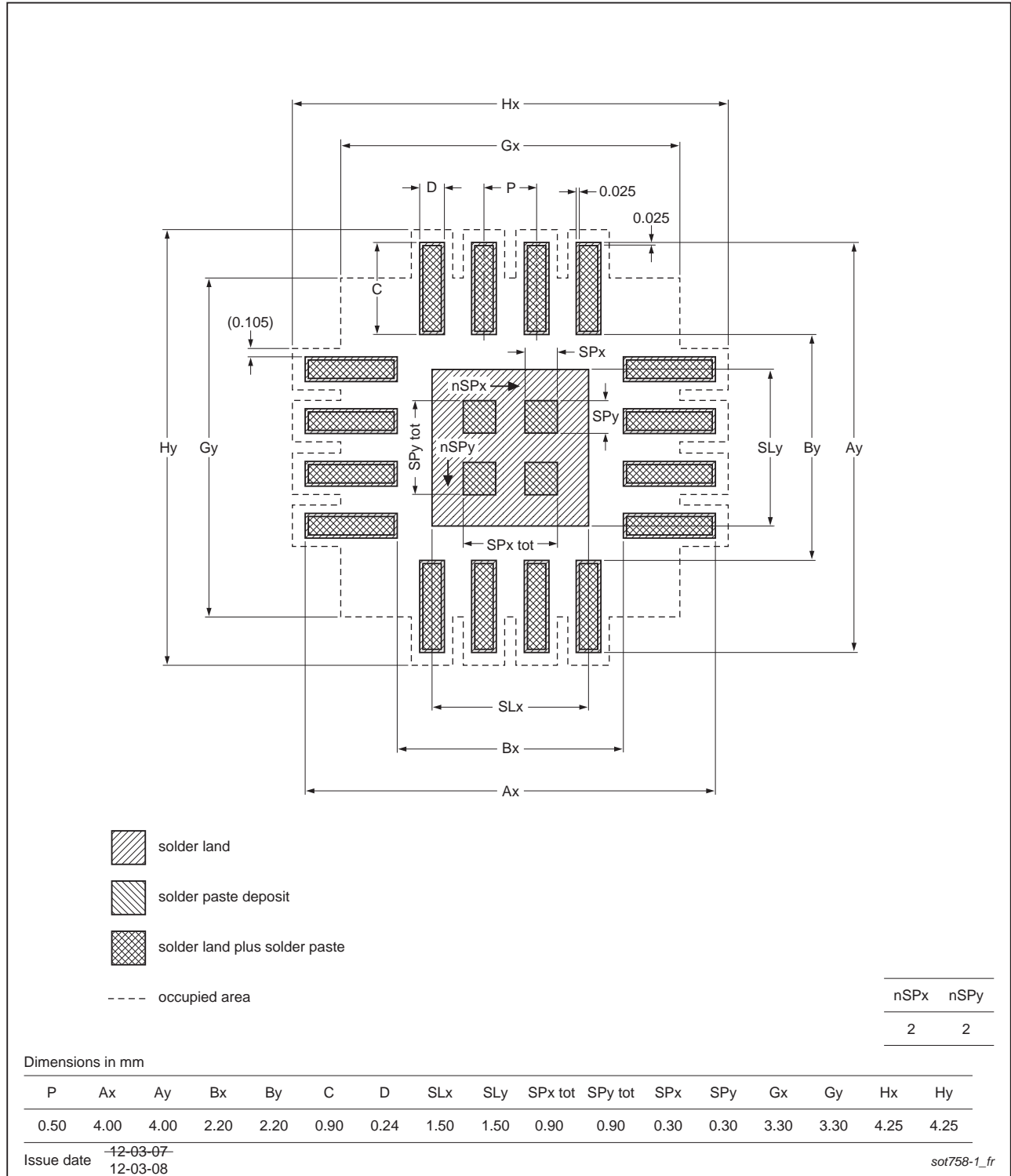


Fig 29. PCB footprint for SOT758-1 (HVQFN16); reflow soldering

15. Abbreviations

Table 14. Abbreviations

| Acronym | Description |
|----------------------|--|
| ACPI | Advanced Configuration and Power Interface |
| CDM | Charged Device Model |
| CMOS | Complementary Metal-Oxide Semiconductor |
| ESD | ElectroStatic Discharge |
| FET | Field-Effect Transistor |
| GPIO | General Purpose Input/Output |
| HBM | Human Body Model |
| I ² C-bus | Inter-Integrated Circuit bus |
| I/O | Input/Output |
| LED | Light-Emitting Diode |
| MM | Machine Model |
| PCB | Printed-Circuit Board |
| POR | Power-On Reset |
| SMBus | System Management Bus |

16. Revision history

Table 15. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------------------------|---|-----------------------|-----------------------------------|-------------------|
| PCA9554_9554A v.10 | 20171108 | Product data sheet | - | PCA9554_9554A v.9 |
| Modifications: | <ul style="list-style-type: none"> • Table 10 "Static characteristics": Corrected V_{POR} typ and max limit | | | |
| PCA9554_9554A v.9 | 20130319 | Product data sheet | - | PCA9554_9554A v.8 |
| Modifications: | <ul style="list-style-type: none"> • Removed DIP16 package option (type numbers PCA9554N and PCA9554AN) • Added Section 3.1 "Ordering options" • Deleted (old) Figure 2, "Pin configuration for DIP16" • Figure 10 "PCA9554A device address" modified: label corrected from "programmable" to "hardware selectable" • Figure 16 "Definition of timing" modified: added $0.7 \times V_{DD}$ and $0.3 \times V_{DD}$ reference lines • Deleted (old) Figure 18, "Package outline SOT38-4 (DIP16)" • Deleted (old) Section 14, "Soldering of through-hole mount packages" • Added Section 14 "Soldering: PCB footprints" | | | |
| PCA9554_9554A v.8 | 20110726 | Product data sheet | - | PCA9554_9554A v.7 |
| PCA9554_9554A v.7 | 20061113 | Product data sheet | - | PCA9554_9554A v.6 |
| PCA9554_9554A v.6 (9397 750 13289) | 20040930 | Product data | - | PCA9554_9554A v.5 |
| PCA9554_9554A v.5 (9397 750 10163) | 20020726 | Product data | 853-2243 28672 of 26 July 2002 | PCA9554_9554A v.4 |
| PCA9554_9554A v.4 (9397 750 09817) | 20020513 | Product specification | - | PCA9554_9554A v.3 |
| PCA9554_9554A v.3 (9397 750 08342) | 20010507 | Product specification | - | PCA9554_9554A v.2 |
| PCA9554_9554A v.2 (9397 750 08209) | 20010319 | Product specification | - | PCA9554_9554A v.1 |
| PCA9554_9554A v.1 (9397 750 08159) | 20010319 | Product specification | - | - |

17. Legal information

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| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
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| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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[2] The term 'short data sheet' is explained in section "Definitions".

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